

**ABSTRACT OF THE DISCLOSURE**

The present invention relates a printed circuit board having jumper lines, and a method for making the printed circuit board. An isolation layer made of a dielectric material is coated on the line layer of the printed circuit board, and multiple pads are formed in the isolation layer, thereby exposing part of the line layer without covered by the isolation layer. A high conductive material is coated on the isolation layer to connect the multiple pads, thereby forming a planar jumper layer that is connected to the line layer through the circular pads. Thus, the planar jumper layer may be made simultaneously during fabrication of the printed circuit board, without having to perform the wire-bonding work.